

## PRODUCT FEATURES

- IGBT Chip(IGBT<sup>3</sup> Trench+Field Stop technology), Diode Chip(Emcon3 wheeling diode)
- Low saturation voltage and positive temperature coefficient
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Industry standard package with insulated copper base plate and soldering pins for PCB mounting
- Temperature sense included



## APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies

## IGBT-inverter

### ABSOLUTE MAXIMUM RATINGS( $T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{CES}$	Collector Emitter Voltage	$T_J=25^{\circ}\text{C}$	1200	V
$V_{GES}$	Gate Emitter Voltage		$\pm 20$	
$I_C$	DC Collector Current	$T_C=25^{\circ}\text{C}$	75	A
		$T_C=80^{\circ}\text{C}$	50	
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1\text{ms}$	100	
$P_{tot}$	Power Dissipation Per IGBT		260	W

## Diode-inverter

### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^{\circ}\text{C}$	1200	V
$I_{F(AV)}$	Average Forward Current	$T_C=25^{\circ}\text{C}$	50	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	100	
$i^2t$		$T_J=125^{\circ}\text{C}$ , $t=10\text{ms}$ , $V_R=0\text{V}$	680	$\text{A}^2\text{S}$

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## IGBT-inverter

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit	
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=2\text{mA}$	5.0	5.8	6.5	V	
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=50\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.7	2.15		
		$I_C=50\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		1.9			
$I_{CES}$	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA	
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$			10	mA	
$I_{GES}$	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 15\text{V}, T_J=25^\circ\text{C}$	-400		400	nA	
$R_{gint}$	Integrated Gate Resistor			4		$\Omega$	
$Q_g$	Gate Charge	$V_{CE}=600\text{V}, I_C=50\text{A}, V_{GE}=\pm 15\text{V}$		0.47		$\mu\text{C}$	
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		3.6		nF	
$C_{res}$	Reverse Transfer Capacitance				160		nF
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=600\text{V}, I_C=50\text{A}$ $R_G=18\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		90		ns
			$T_J=125^\circ\text{C}$		90		ns
$t_r$	Rise Time	Inductive Load	$T_J=25^\circ\text{C}$		30		ns
			$T_J=125^\circ\text{C}$		50		ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=600\text{V}, I_C=50\text{A}$ $R_G=18\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		420		ns
			$T_J=125^\circ\text{C}$		520		ns
$t_f$	Fall Time	Inductive Load	$T_J=25^\circ\text{C}$		70		ns
			$T_J=125^\circ\text{C}$		90		ns
$E_{on}$	Turn on Energy	$V_{CC}=600\text{V}, I_C=50\text{A}$ $R_G=18\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		4.9		mJ
			$T_J=125^\circ\text{C}$		6.6		mJ
$E_{off}$	Turn off Energy	Inductive Load	$T_J=25^\circ\text{C}$		4		mJ
			$T_J=125^\circ\text{C}$		4.9		mJ
$I_{sc}$	Short Circuit Current	$tpsc \leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=900\text{V}$		200		A	
$R_{thJC}$	Junction to Case Thermal Resistance ( Per IGBT)				0.48	K/W	

## Diode-inverter

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=50\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.65	2.15	V
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.65		
$t_{rr}$	Reverse Recovery Time	$I_F=50\text{A}, V_R=600\text{V}$		360		ns
$I_{RRM}$	Max. Reverse Recovery Current	$di_F/dt=-1200\text{A}/\mu\text{s}$		50		A
$Q_{RR}$	Reverse Recovery Charge	$T_J=125^\circ\text{C}$		9.5		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy				4.4	
$R_{thJCD}$	Junction to Case Thermal Resistance ( Per Diode)				0.78	K/W

**NTC CHARACTERISTICS** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$R_{25}$	Resistance	$T_C = 25^\circ\text{C}$		5		K $\Omega$
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15 \text{ K}))]$			3375		K

**MODULE CHARACTERISTICS** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$T_{Jmax}$	Max. Junction Temperature		150	$^\circ\text{C}$
$T_{Jop}$	Operating Temperature		-40~125	
$T_{stg}$	Storage Temperature		-40~125	
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
CTI	Comparative Tracking Index		>225	
Md	Mounting Torque	Recommended (M5)	2.5~5	Nm
Weight			180	g

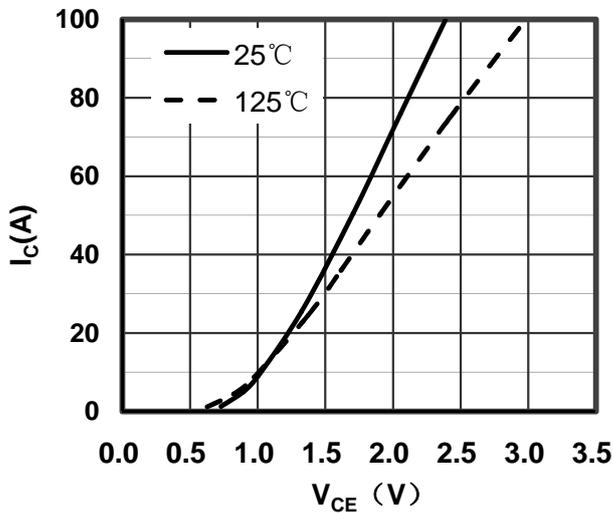


Figure 1. Typical Output Characteristics IGBT-inverter

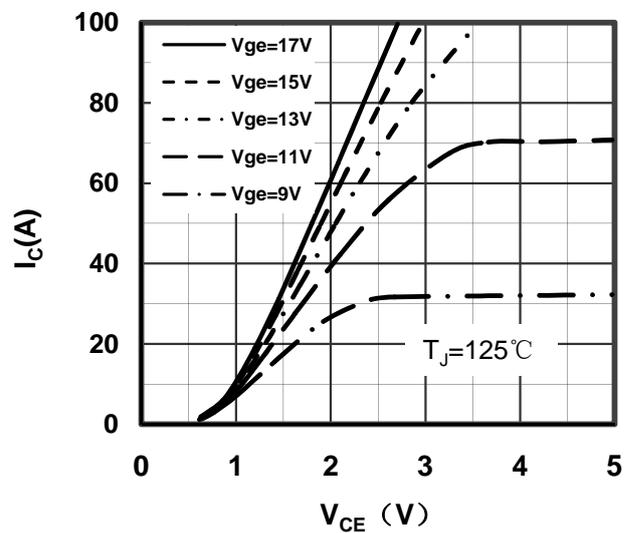


Figure 2. Typical Output Characteristics IGBT-inverter

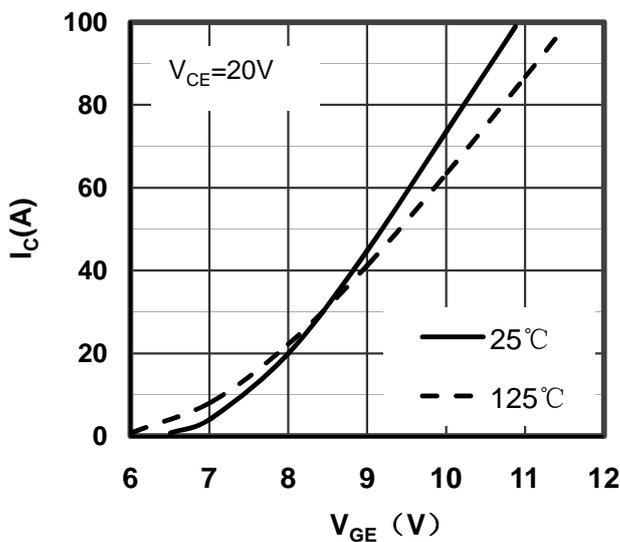


Figure 3. Typical Transfer Characteristics IGBT-inverter

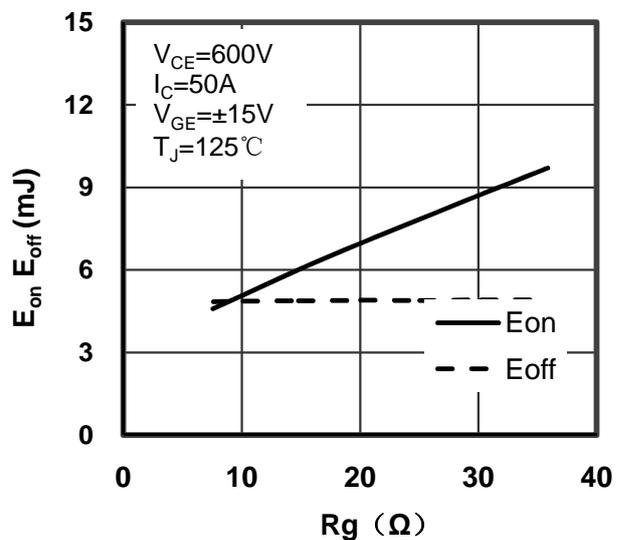


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

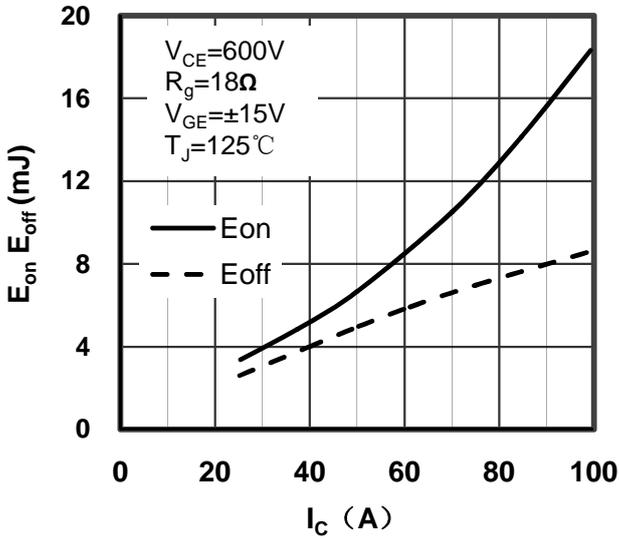


Figure 5. Switching Energy vs Collector Current IGBT-inverter

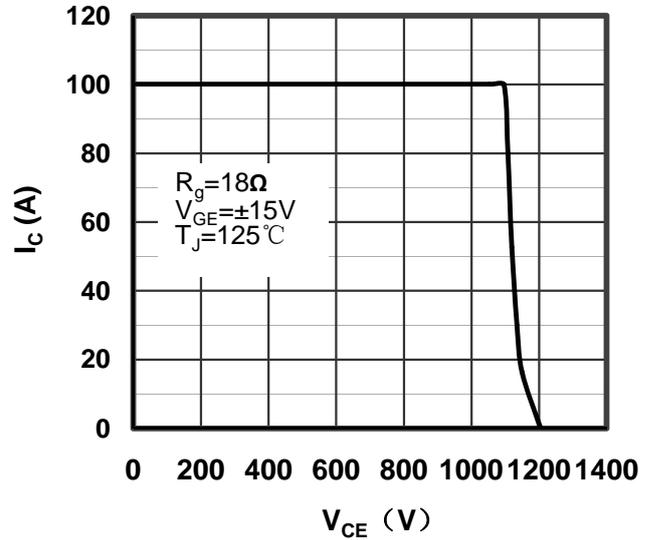


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

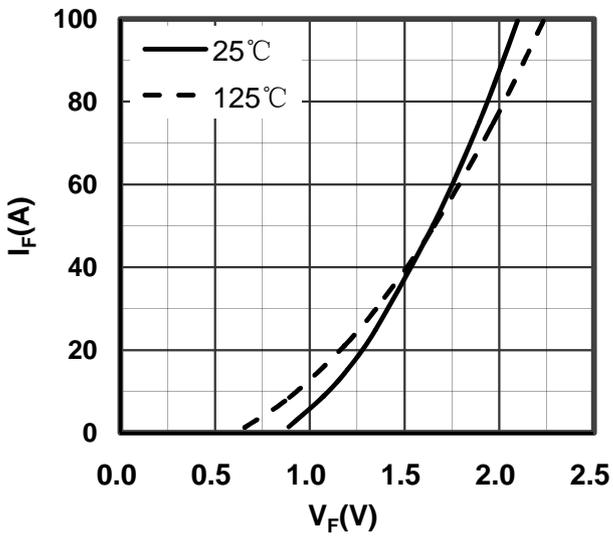


Figure 7. Diode Forward Characteristics Diode -inverter

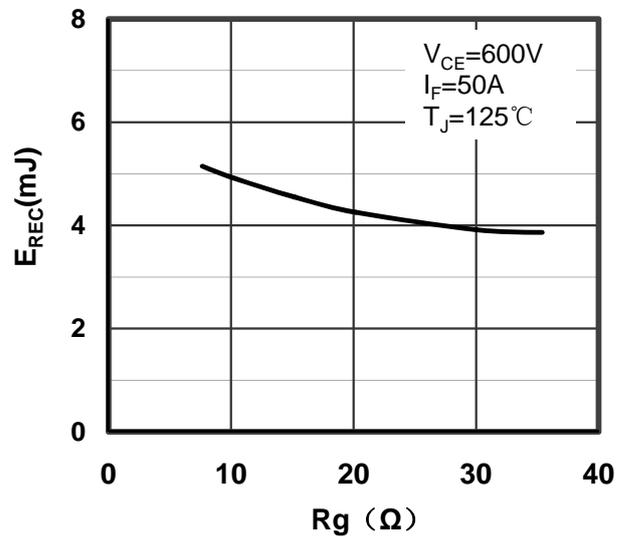


Figure 8. Switching Energy vs Gate Resistor Diode -inverter

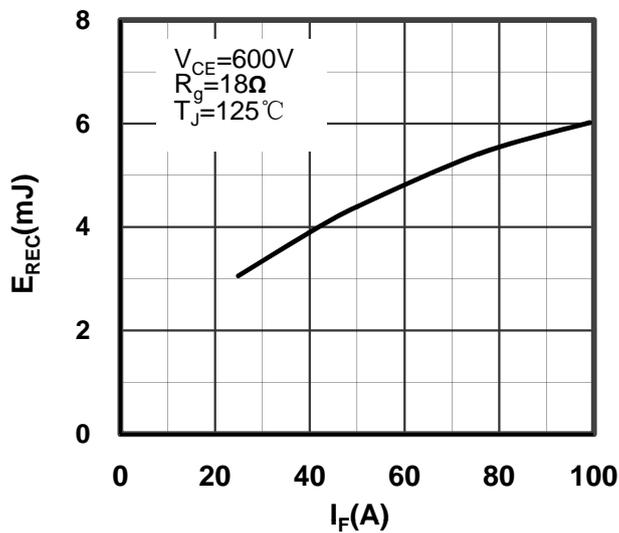


Figure 9. Switching Energy vs Forward Current Diode-inverter

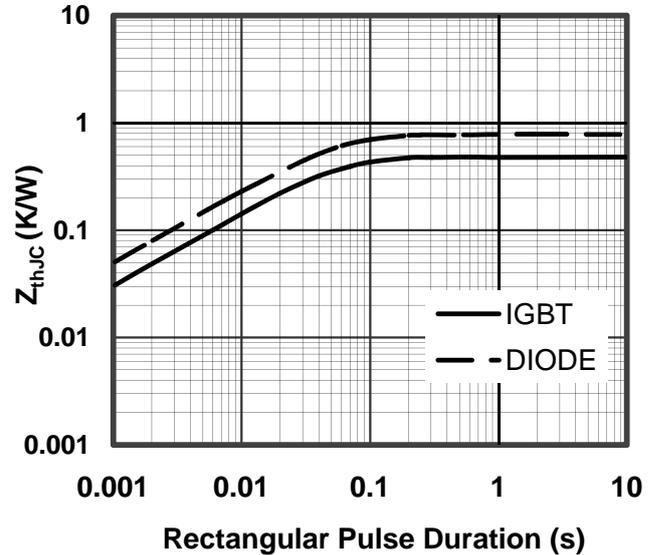


Figure 10. Transient Thermal Impedance of Diode and IGBT-inverter

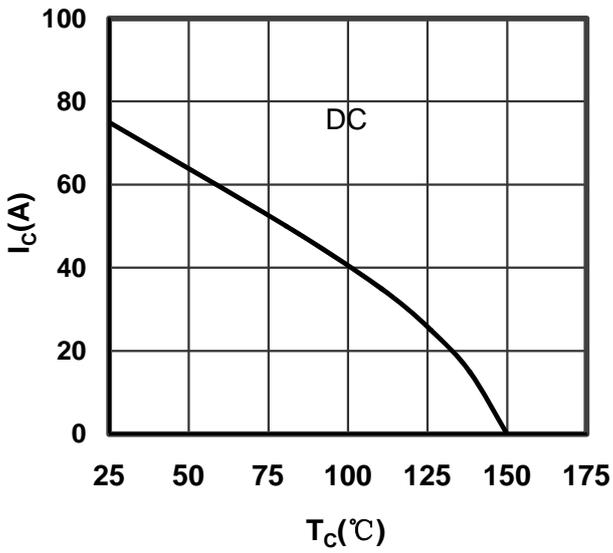


Figure 11. Collector Current vs Case temperature IGBT -inverter

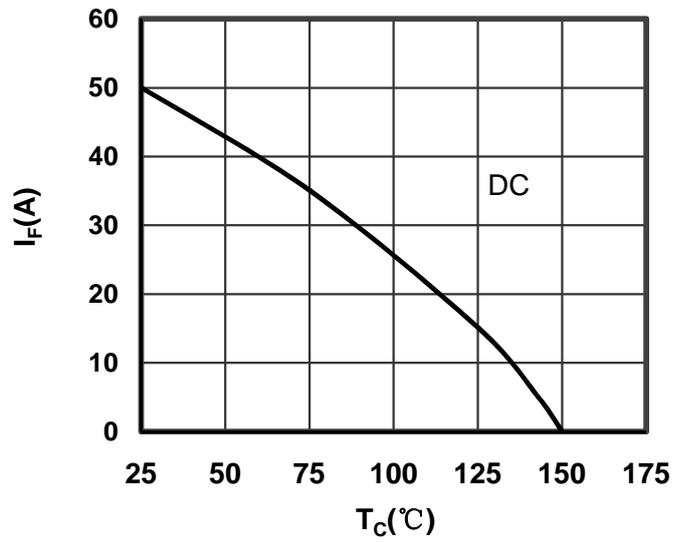


Figure 12. Forward current vs Case temperature Diode -inverter

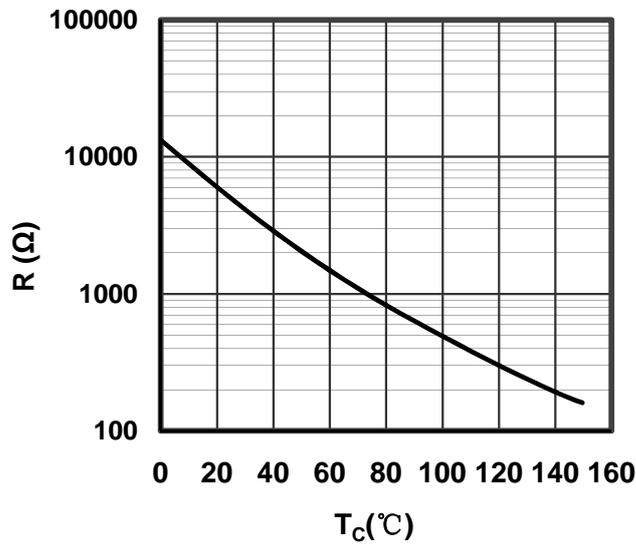


Figure 13. NTC Characteristics

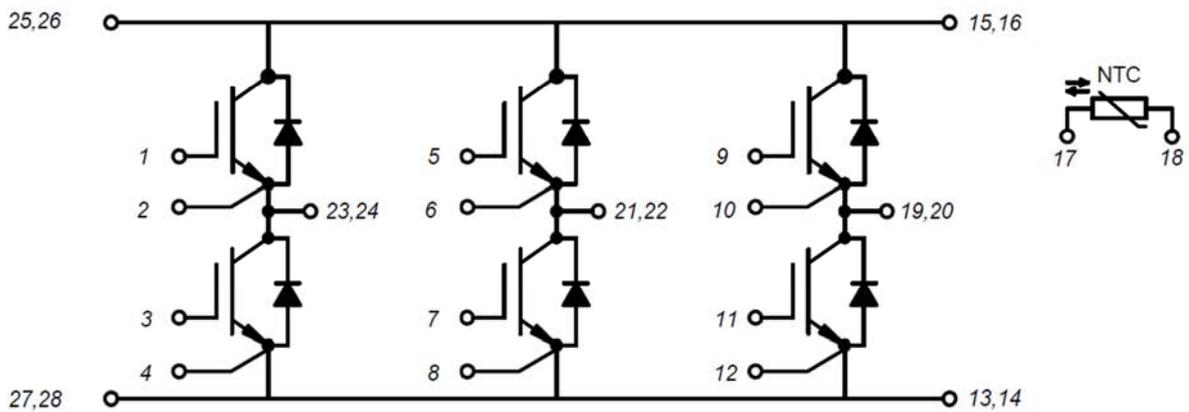
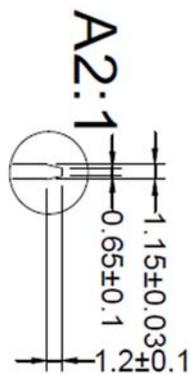
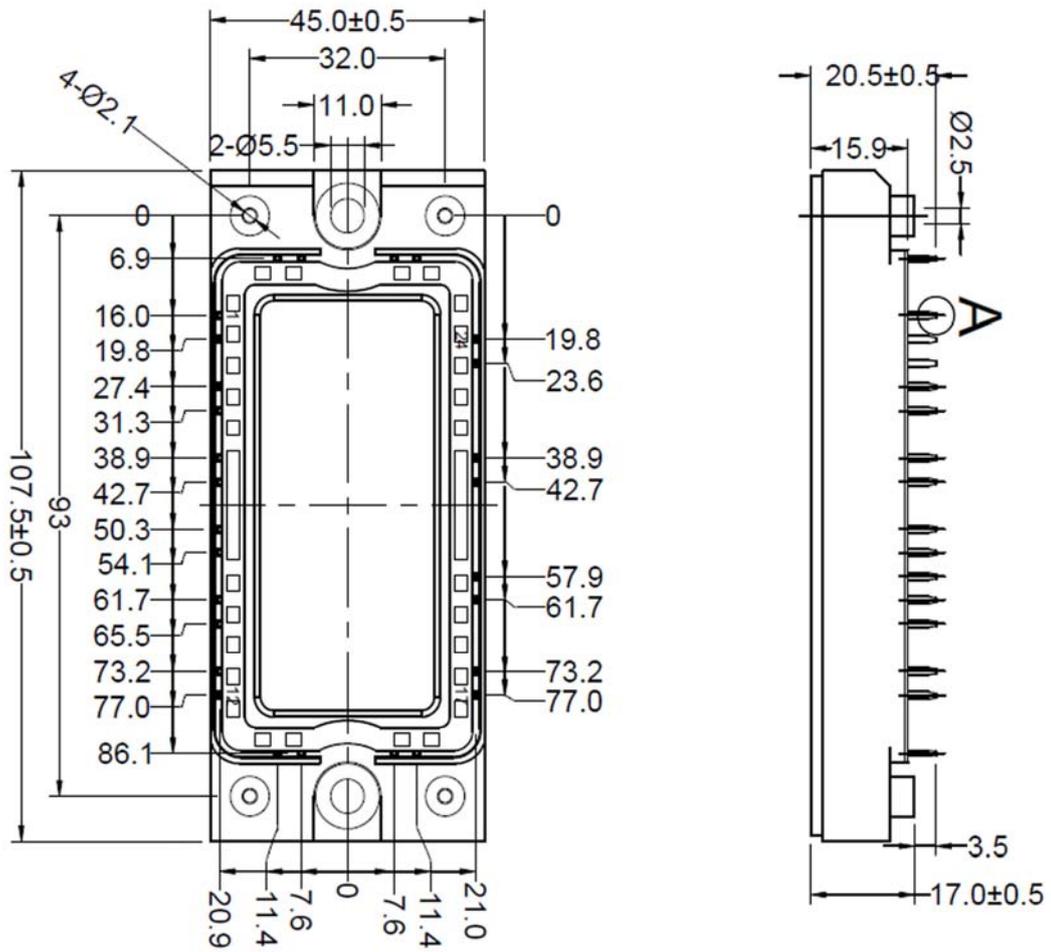


Figure 14. Circuit Diagram



Dimensions in (mm)  
Figure 15. Package Outline